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(12) **United States Design Patent**  
**Yoshida et al.**

(10) **Patent No.:** **US D933,032 S**  
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(54) **SEAL MEMBER FOR SEMICONDUCTOR PRODUCTION APPARATUS**

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(\*\*) Term: **15 Years**

(Continued)

(21) Appl. No.: **29/750,937**

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(22) Filed: **Sep. 17, 2020**

“High Performance FKM” found by RMS on the internet at: [https://valqua-america.com/products/semiconductor\\_b.html](https://valqua-america.com/products/semiconductor_b.html) reference dated Mar. 24, 2021.\*

**Related U.S. Application Data**

(62) Division of application No. 35/507,483, filed on Apr. 1, 2019 (U.S. filing date under 35 U.S.C. 384), and having an international filing date of Apr. 1, 2019, now Pat. No. Des. 909,322.

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(30) **Foreign Application Priority Data**

(57) **CLAIM**

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Oct. 12, 2018 (JP) ..... 2018-022467  
Oct. 12, 2018 (JP) ..... 2018-022468  
Oct. 12, 2018 (JP) ..... 2018-022469

The ornamental design for a seal member for semiconductor production apparatus, as shown and described.

(51) **LOC (13) Cl.** ..... **13-03**

**DESCRIPTION**

(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**  
USPC ..... D13/199; D4/137; D9/416; D23/269;  
D15/7  
CPC ..... C08K 5/0025; F16K 3/0227; F16K 51/02;  
F16J 15/062; F16J 15/025; F16J 15/3488  
See application file for complete search history.

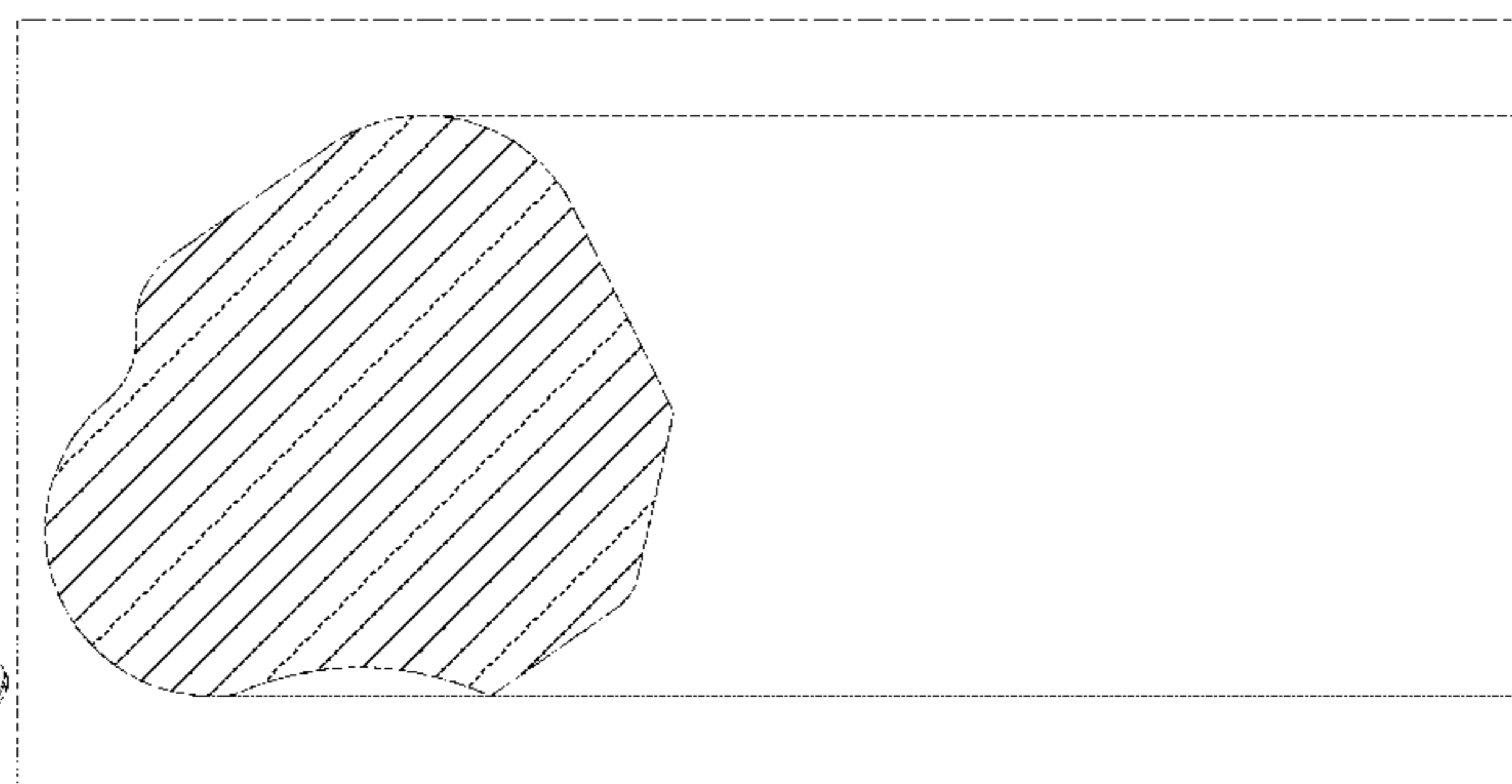
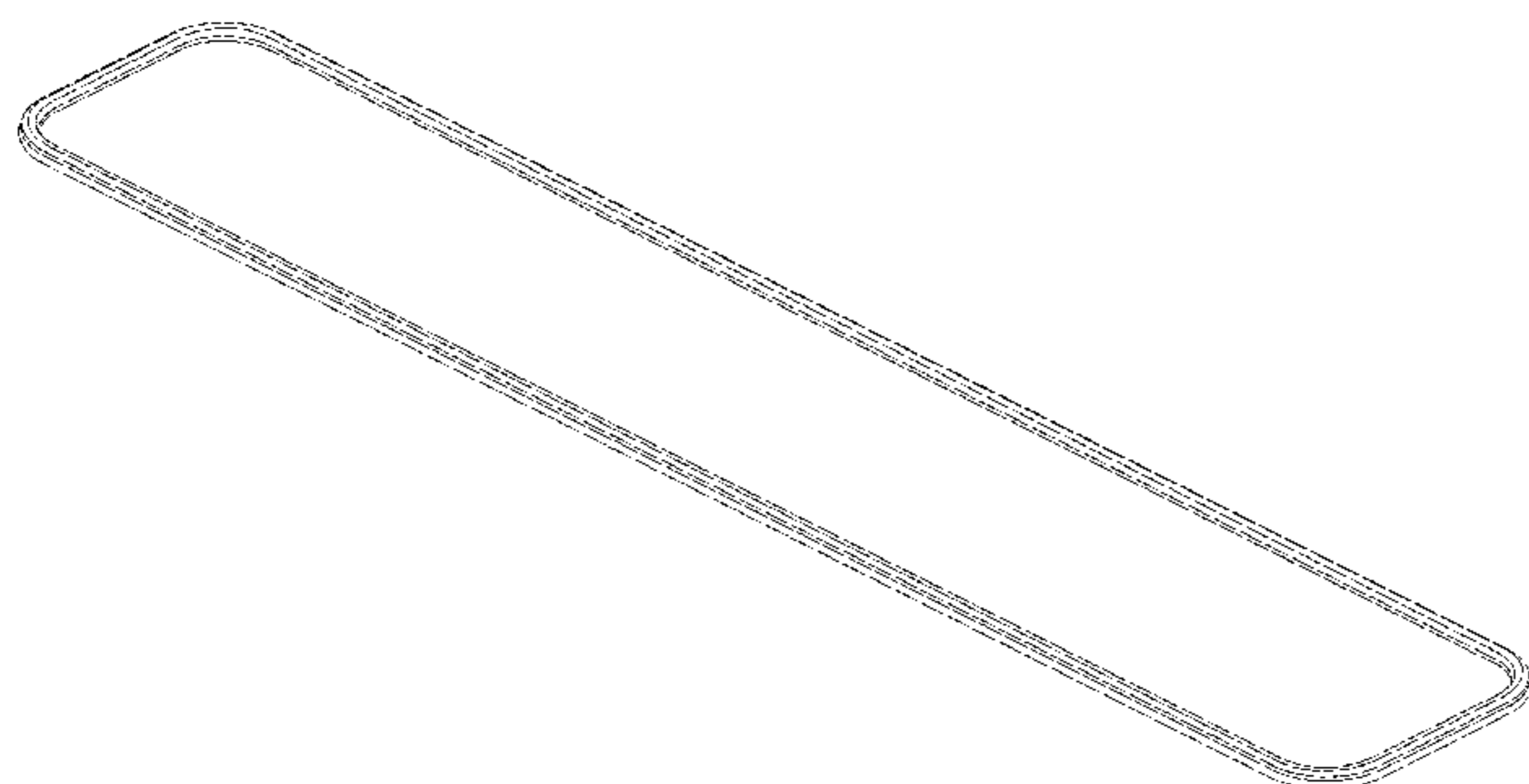
FIG. 1 is a perspective view of a seal member for semiconductor production apparatus, showing our new design;  
FIG. 2 is a front elevation view thereof;  
FIG. 3 is a rear elevation view thereof;  
FIG. 4 is a left side elevation view thereof;  
FIG. 5 is a right side elevation view thereof;  
FIG. 6 is a top view thereof;  
FIG. 7 is a bottom view thereof;  
FIG. 8 is a cross-sectional view thereof taken along line 8-8 shown in FIG. 6; and,  
FIG. 9 is an enlarged cross-sectional view of a portion thereof taken from area 9-9 shown in FIG. 8.

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**1 Claim, 9 Drawing Sheets**



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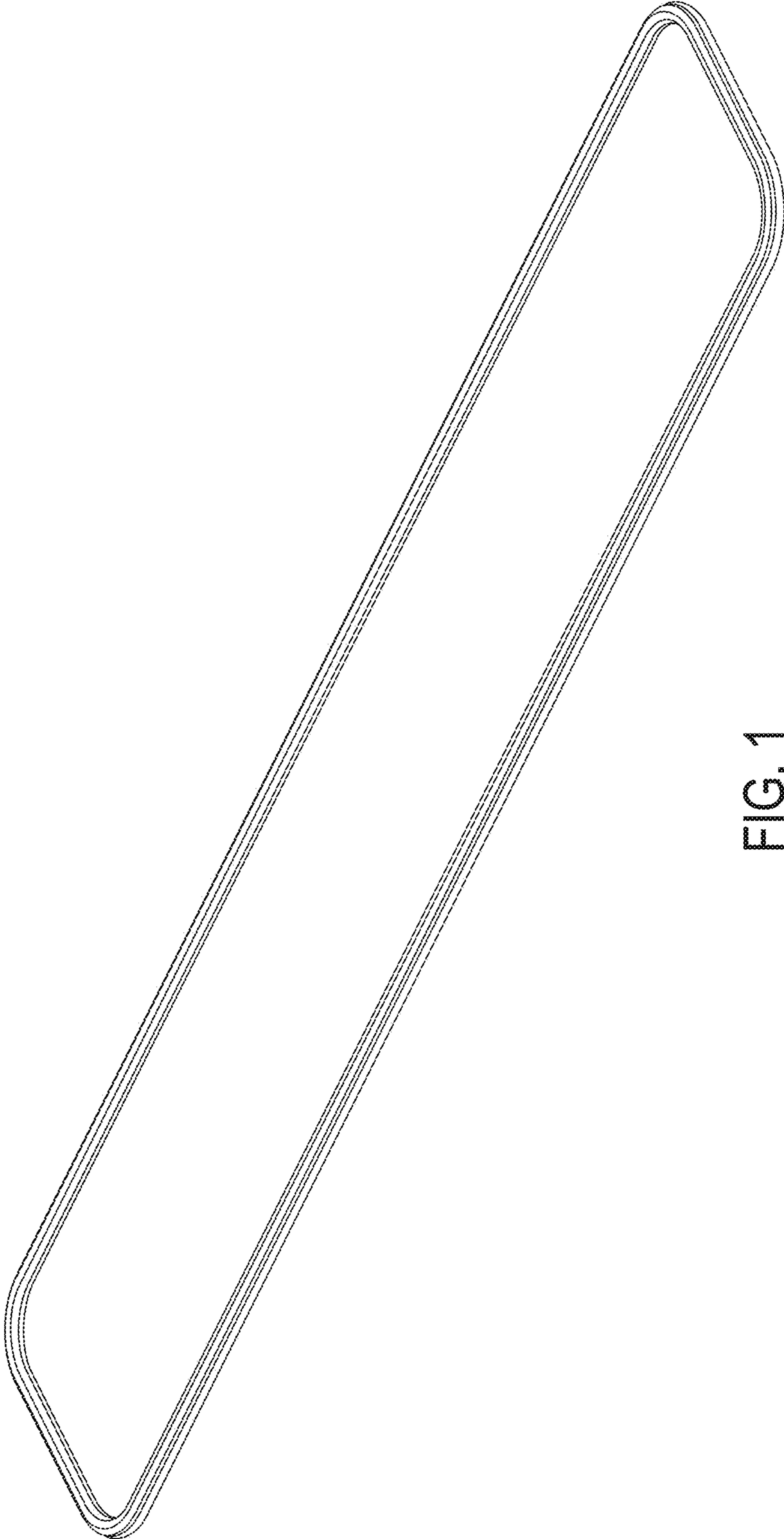


FIG. 1

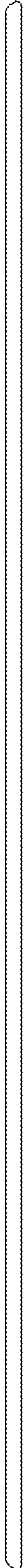


FIG. 2



FIG. 3

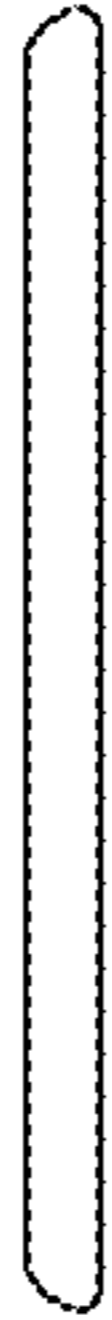


FIG. 4

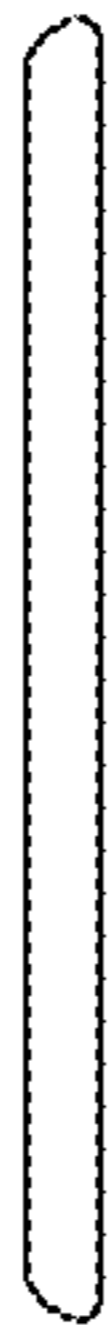


FIG. 5

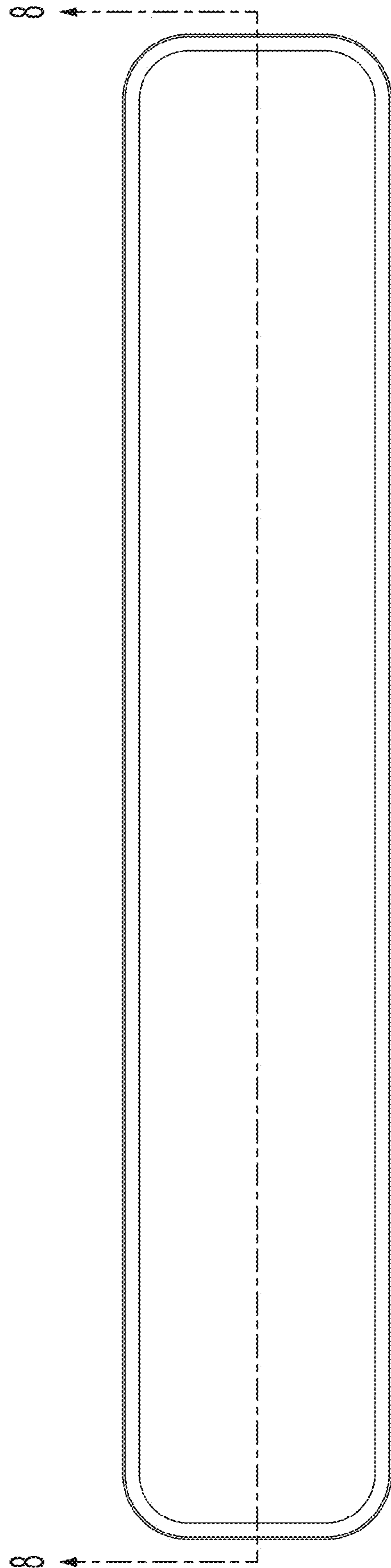


FIG. 6



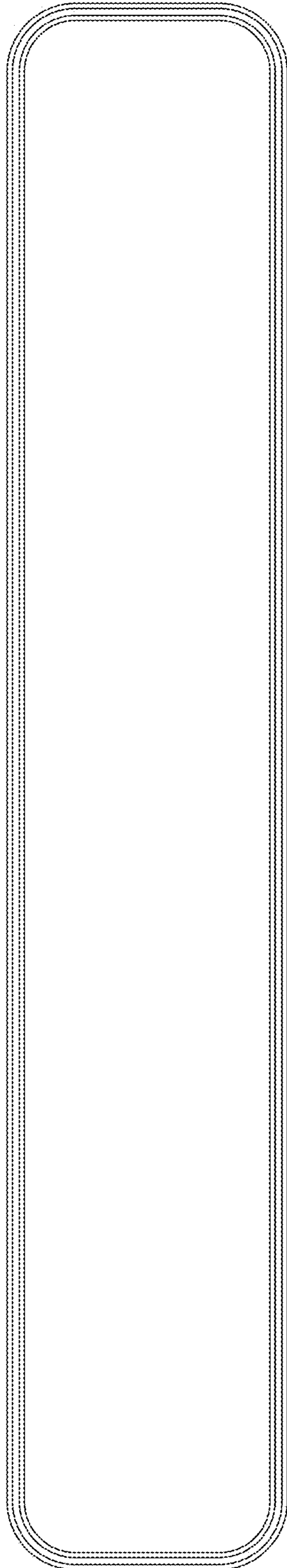


FIG. 7

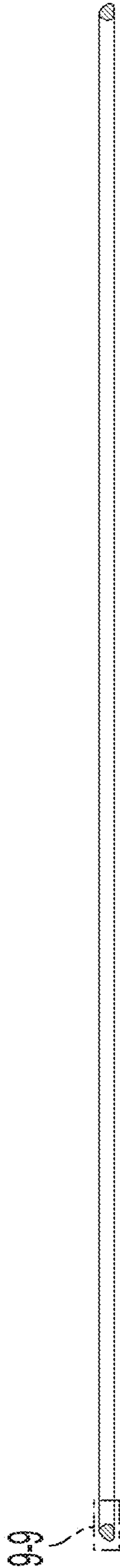


FIG. 8

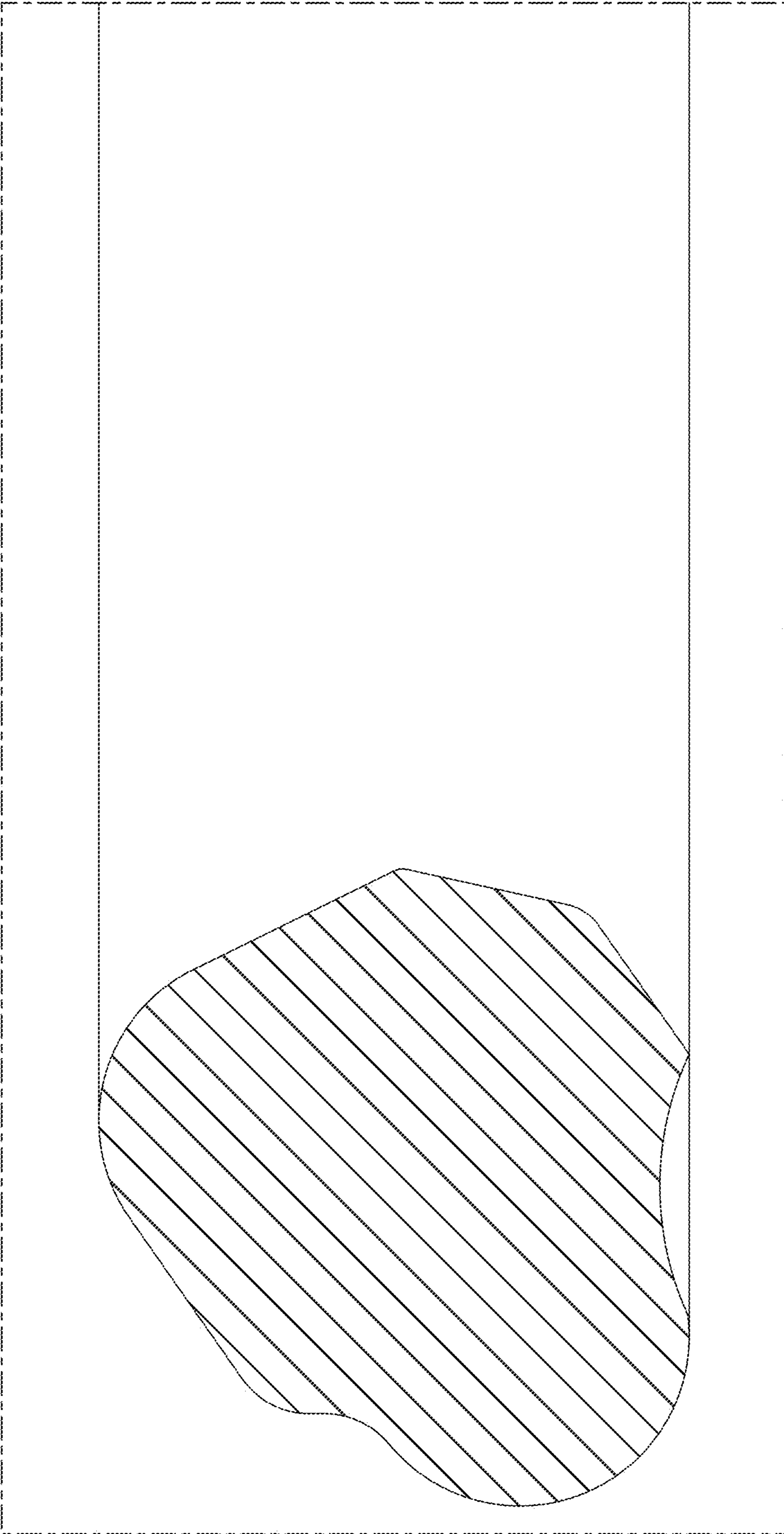


FIG. 9